



Material Content Data Sheet



Sales Product Name		BSC0909NS		Issued		29. August 2013		
MA#		MA001109436						
Package		PG-TDSON-8-14		Weight*		118.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.614	0.52	0.52	5180	5180
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82	
	non noble metal	zinc	7440-66-6	0.039	0.03		328	
	non noble metal	iron	7439-89-6	0.778	0.66		6566	
wire	non noble metal	copper	7440-50-8	31.590	26.66	27.36	266615	273591
	non noble metal	copper	7440-50-8	0.054	0.05	0.05	455	455
encapsulation	organic material	carbon black	1333-86-4	0.242	0.20		2043	
	plastics	epoxy resin	-	7.504	6.33		63330	
	inorganic material	silicondioxide	60676-86-0	40.665	34.33	40.86	343208	408581
leadfinish	non noble metal	tin	7440-31-5	1.243	1.05	1.05	10487	10487
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	316	316
solder	noble metal	silver	7440-22-4	0.024	0.02		206	
	non noble metal	tin	7440-31-5	0.020	0.02		165	
	non noble metal	lead	7439-92-1	0.932	0.79	0.83	7865	8236
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	zinc	7440-66-6	0.021	0.02		180	
	non noble metal	iron	7439-89-6	0.428	0.36		3608	
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.65	15.03	146515	150348
	non noble metal	iron	7439-89-6	0.017	0.01		143	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	copper	7440-50-8	16.898	14.26	14.27	142620	142806
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com